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Under the Peperwork Reduction Act of 1995, no perso	Application Number	llaction of information unless it displays a valid OMB control number.		
TRANSMITTAL	Filing Date	10/052,466		
FORM	First Named Inventor	January 23, 2002		
FORIVI	Art Unit	Ming-Kwei LEE		
·	Examiner Name			
(to be used for all correspondence after initial filing)		Owens, Douglas W.		
Total Number of Pages in This Submission 4	Attorney Docket Number	70434.00024		
ENC	LOSURES (Check all	that apply)		
Fee Transmittal Form	Drawing(s)	After Allowance Communication to TC		
Fee Attached	Licensing-related Papers	Appeal Communication to Board of Appeals and Interferences		
- Antionemotic ply	Petition	Appeal Communication to TC (Appeal Notice, Brief, Reply Brief)		
	Petition to Convert to a Provisional Application	Proprietary Information		
	Power of Attorney, Revocation			
	Change of Correspondence A	Other Enclosure(s) (please Identify		
Extension of Time Request	Terminal Disclaimer	Delow);		
Express Abandonment Request	Request for Refund	Request for Certificate of Correction Under 37 C.F.R.§1.322 and Copy of first page of		
Information Disclosure Statement	CD, Number of CD(s)	U.S. Patent No. 6,858,873		
[Landacape Table on CD			
Certified Copy of Priority Remai	rks			
Document(s)				
Reply to Missing Parts/ Incomplete Application				
Reply to Missing Parts under 37 CFR 1.52 or 1.53				
		·		
SIGNATURE	F APPLICANT, ATTOR	RNEY OR AGENT		
Firm Name Dickinson Wright PLLC				
Signature				
Printed name	Veg			
John M. Naber	· /			
November 14, 2005	R	eg. No. 46,487		
CERTIFIC	ATE OF TRANSMISSI	DN/MAILING		
I hereby carlify that this correspondence is being facsin sufficient postage as first class mail in an envelope and the date shown below:	nile transmitted to the USPTC reased to: Commissioner for	or deposited with the United States Postal Service with Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on		
Signature	ll			
Typed or printed name Anita B. Brozeli		Date November 14, 2005		

This collection of information is required by 37 CFR 1.5. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11 and 1.14. This collection is estimated to 2 hours to complete, including gethering, preparing, and submitting the completed application form to the USPTO. Time will very depending upon the individual case. Any comments on the amount of time you require to complete this form end/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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Attorney Docket No.: 70434.00024

Customer No.: 35161

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Ming-Kwei LEE

Group Art Unit: 2811

Application No.: 10/052,466

Examiner: Owens, Douglas W.

Patent Number: 6,858,873

Confirmation No.: 6427

Issued: February 22, 2005

Filed: January 23, 2002

Semiconductor Diode Having A Semiconductor Die With A Substrate and Multiple

Films Applied Thereover

REQUEST FOR CERTIFICATE OF CORRECTION UNDER 37 CFR 1.322

Attention: Certificate of Corrections Branch
Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

For:

Patentee requests that an issued patent be corrected. A copy of the Certificate of Correction, issued by the U.S. Patent and Trademark Office on February 22, 2005, is attached hereto. In support of this, a copy of the first page of the issued patent is attached hereto. The missing assignee data has been circled in red and should read as noted below in the appropriate area of the issued patent.

The name of the Assignee is as follows:

CHIA TA WORLD CO., LTD.
No. 16, Lane 317, Chung-Shan N. Rd.
Yung-Kang City, Tainan Hsien, Taiwan

Accordingly, patentee respectfully requests a Certificate of Correction be issued for the referenced patent, and if the Office deems it appropriate, issuance of corrected Letters Patent. Since the error is the result of Patent Office mistake, no fee is required or submitted.

Request for Certificate of Correction U.S. Patent 6,858,873

Atty Dkt. No.: 70434.00024

However, if this is found to the contrary, please charge any shortage in fees in connection with the filing of this paper, including extension of times fees, to Deposit Account number 04-0160 and please credit any excess fees to such account.

Respectfully submitted,

M. Naber

Registration No. 46,487

DICKINSON WRIGHT PLLC 1901 L St., N.W. Suite 800 Washington, D.C. 20036 Telephone: 202/659-6946

Facsimile: 202/659-1559 Date: November 14, 2005

(12) United States Patent

(10) Patent No .:

US 6,858,873 B2

(45) Date of Patent:

Feb. 22, 2005

(54)	SEMICONDUCTOR DIODE HAVING A SEMICONDUCTOR DIE WITH A SUBSTRATE AND MULTIPLE FILMS
	APPLIED THEREOVER

Inventor: Ming-Kwei Lee, 4F-4, No. 171

Pi-Chung St., Yen-Cheng Dist., Kaohsiung City (TW)

(*) Notice:

Subject to any disclaimer, the term of this patent is extended or adjusted under \$5 U.S.C. 154(b) by 70 days.

(21) Appl. No.: 10/052,466

(22)Filed: Jan. 23, 2002

(65)

Prior Publication Data

US 2003/0136955 AI Jul. 24, 2003

(51) Int. Cl.⁷ H01L 29/267

(58) Field of Search

257/81, 79, 84,

257/99, 46

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Primary Examiner-Eddic Lee Assistant Examiner-Douglas W. Owens

ABSTRACT

A semiconductor diode has a semiconductor die that includes a substrate, a first semiconductor film, a second semiconductor film, a first metal contact, and a second metal contact. The semiconductor die defines two diagonally opposite first corners and two diagonally opposite second corners. The first semiconductor film has an exposed area that is exposed from the second semiconductor film and that extends between one of the first corners and one of the second corners. The first metal contact is formed on the exposed area and has an extension section and a wirebonding section that has a width greater than that of the extension section and a length less than that of the extension section. The second metal contact extends between the other one of the first comers and the other one of the second corners and has an extension section and a wire-bonding section that has a width greater than that of the extension section and a length less than that of the extension section.

17 Claims, 4 Drawing Sheets

